

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3	("20020060091" "6013357" "6569514").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 08:15
S2	16	((TOSHIYUKI) near2 (NAGASE)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/30 08:23
S3	10	((YOSHIYUKI) near2 (NAGATOMO)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/30 08:23
S4	12	((KAZUAKI) near2 (KUBO)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/30 08:23
S5	9	((TAKESHI) near2 (NEGISHI)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/30 08:23
S6	178	((TOSHIYUKI) near2 (NAGASE)).INV.	EPO; JPO; DERWENT	AND	ON	2008/07/30 08:23
S7	73	((YOSHIYUKI) near2 (NAGATOMO)).INV.	EPO; JPO; DERWENT	AND	ON	2008/07/30 08:23
S8	66	((KAZUAKI) near2 (KUBO)).INV.	EPO; JPO; DERWENT	AND	ON	2008/07/30 08:23
S9	94	((TAKESHI) near2 (NEGISHI)).INV.	EPO; JPO; DERWENT	AND	ON	2008/07/30 08:23
S10	18735	(MITSUBISHI near2 MATERIALS).as.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 08:25
S11	199	(S2 or S3 or S4 or S5 or S6 or S7 or S8 or S9) S10	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 08:25
S12	79	S11 (base or plate)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 08:50
S13	20	S12 (ceramic metal)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 08:50
S14	3483	361/704.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:02
S15	146	S14 (base plate ceramic metal (power or transistor) (heatsink or (heat adj sink)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:03

S16	8	S15 (release near3 (agent or material))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:04
S17	2	361/705-709.ccls. ((power adj modul\$4) base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:06
S18	12	("4712160" "5172213" "5398160" "5608610" "6201696" "6282092" "6473304").PN. OR ("7057896").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/30 09:06
S19	0	S18 ((power adj modul\$4) base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:06
S20	0	361/717.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:13
S21	0	165/80.2.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:13
S22	0	165/104.33.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:13
S23	1	257/705-707.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:13
S24	0	257/713.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:14
S25	0	257/720.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:14

S26	0	62/259.2.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:14
S27	0	468/650.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:14
S28	0	468/210.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:14
S29	1	S10 ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:15
S30	1	(S2 or S3 or S4 or S5 or S6 or S7 or S8 or S9) ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:15
S31	6	"361"/\$.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:15
S32	5	"428"/\$.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:16
S33	2	"165"/\$.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:17
S34	12	"257"/\$.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:17
S35	0	"62"/\$.ccls. ((power adj modul\$4) joint base plate ceramic metal boron (chip or IC or semiconductor or circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:18

S36	1	((power adj modul\$4) (joint near2 material) plate ceramic metal aluminum nitr\$4 boron (chip or IC or semiconductor or integrated))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:20
S37	162	((power adj modul\$4) material ((aluminum adj nitride) or AlN) ((boron adj nitride) or BN) (chip or IC or semiconductor or integrated))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:22
S38	83	S37 (heatsink or (heat adj (sink or plate)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:28
S39	18	("20020037435" "20020164488" "20040149689" "3390564" "4530151" "4552301" "4602731" "4699310" "4929433" "5144885" "5196756" "5543130" "5571603" "6066205" "6183875" "6309737" "6670216"). PN. OR ("7073703"). URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/30 09:32
S40	1	(10/087566).APP.	USPAT; USOCR	AND	ON	2008/07/30 09:34
S41	11	("20010017770" "3994430" "4222774" "5213877" "5707715" "5807626" "5965193" "6033787" "6122170" "6153025" "6297549"). PN. OR ("7276292"). URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/30 09:34
S42	25	("4634041" "4657825" "4693409" "4835344" "4849292" "4919731" "5328751" "5354415" "5561321").PN. OR ("5807626").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/30 09:35

S43	37	(US-20070274047-\$ or US-20050214518-\$ or US-20040070946-\$ or US-20040018945-\$ or US-20050035438-\$ or US-20040207053-\$ or US-20040145046-\$ or US-20040089928-\$ or US-20040074951-\$ or US-20020179289-\$ or US-20020037435-\$ or US-20040149689-\$ or US-20020164488-\$).did. or (US-6483185-\$ or US-6033787-\$ or US-6707671-\$ or US-6054198-\$ or US-6214446-\$ or US-6013357-\$ or US-6311888-\$ or US-6522555-\$ or US-6309737-\$ or US-5354415-\$ or US-4876119-\$ or US-5807626-\$ or US-5571603-\$ or US-4929433-\$ or US-4699310-\$ or US-4602731-\$ or US-4552301-\$ or US-5213877-\$ or US-7189449-\$ or US-7170186-\$ or US-6877651-\$ or US-6485816-\$ or US-6328198-\$ or US-4693409-\$).did.	US-PGPUB; USPAT	AND	ON	2008/07/30 09:41
S44	23	S43 (boron or BN)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:41
S45	1	S44 (crystal grain strain \$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:44
S46	1	S43 (crystal grain strain \$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:44
S47	1254	(join\$4 metal ceramic (crystal grain strain\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:45

S48	58	S47 (((aluminum adj nitride) or AlN) ((boron adj nitride) or BN))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 09:46
S49	2	((plate or substrate) ceramic metal join\$4 ((boron adj nitride) or BN) (crystal near3 grain near3 strain\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:06
S50	346	((plate or substrate) ceramic metal join\$4 ((boron adj nitride) or BN) (crystal with (grain or strain\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:08
S51	166	S50 (xray or (x adj ray))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:09
S52	92	S51 ((xray or (x adj ray)) with (analy\$4 or test))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:09
S53	50	(US-20070274047-\$ or US-20050214518-\$ or US-20040070946-\$ or US-20040018945-\$ or US-20050035438-\$ or US-20040207053-\$ or US-20040145046-\$ or US-20040089928-\$ or US-20040074951-\$ or US-20020179289-\$ or US-20020037435-\$ or US-20040149689-\$ or US-20020164488-\$ or US-20040175549-\$ or US-20040094871-\$ or US-20030170415-\$ or US-20020150789-\$ or US-20020051848-\$ or US-20050014031-\$ or US-20040207072-\$ or US-20030203225-\$ or US-20030089975-\$ or US-20030044653-\$).did. or (US-6483185-\$ or US-6033787-\$ or US-6707671-\$ or US-6054198-\$ or US-6214446-\$ or US-6013357-\$ or US-6311888-\$ or US-6522555-\$ or US-6309737-\$ or US-	US-PGPUB; USPAT	AND	ON	2008/07/30 10:53

		5354415-\$ or US- 4876119-\$ or US- 5807626-\$ or US- 5571603-\$ or US- 4929433-\$ or US- 4699310-\$ or US- 4602731-\$ or US- 4552301-\$ or US- 5213877-\$ or US- 7189449-\$ or US- 7170186-\$ or US- 6877651-\$ or US- 6485816-\$ or US- 6328198-\$ or US- 4693409-\$ or US- 5834840-\$ or US- 5392982-\$).did. or (US- 5248079-\$).did.				
S54	36	S53 (boron or BN)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:54
S55	21	S54 crystal	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:54
S56	6	S55 ((grain) near2 crystal)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:54
S57	4	"361"/\$.ccls. (crystal with grain with strain)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:57
S58	82	"428"/\$.ccls. (crystal with grain with strain)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:58
S59	26	S58 (ceramic metal)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:58
S60	7	S59 (bond or join)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 10:59
S61	7	(metal ceramic (bond or join) ((amount or percent) SAME (crystal with grain with strain)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:10

S62	0	((metal ceramic) SAME (bond or join)) (crystal with grain with strain) green sinter)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:14
S63	137	((metal ceramic) SAME (bond or join)) (crystal with grain) green)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:15
S64	49	S63 strain	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:15
S65	0	S64 ((grain or strain) with (amount of percent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:15
S66	0	S64 ((grain or strain) SAME (amount of percent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:16
S67	54	S63 (boron or BN)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:16
S68	26	S63 ((nitride near2 boron) or BN)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:16
S69	14079	(fluoresc\$4 near2 (xray or (x adj ray)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:19
S70	24	S69 (((metal ceramic) WITH (bond or join)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:20
S71	910	S69 (crystal with (grain or strain))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:21
S72	1	S71 (((metal ceramic) WITH (bond or join)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:21
S73	389	S71 (bond or join)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:22

S74	6631	"I2" (metal ceramic)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:22
S75	283	"I25" (metal ceramic)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:22
S76	138	S75 "428"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 11:23
S77	0	("(40%(crystalnear4 (grainorstrain)))").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2008/07/30 13:31
S78	0	("(40%(crystalnear4 (grainstrain)))").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2008/07/30 13:31
S79	0	("(40%(crystalnear4 (grainstrain)))").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2008/07/30 13:31
S80	0	("(40(crystalnear4 (grainstrain)))").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2008/07/30 13:31
S81	0	("000040%").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2008/07/30 13:31
S82	67	"361"/\$.ccls. (fluoresc\$4 near3 (xray or (x adj ray)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 13:34
S83	60	(US-20070274047-\$ or US- 20050214518-\$ or US- 20040070946-\$ or US- 20040018945-\$ or US- 20050035438-\$ or US- 20040207053-\$ or US- 20040145046-\$ or US- 20040089928-\$ or US- 20040074951-\$ or US- 20020179289-\$ or US- 20020037435-\$ or US- 20040149689-\$ or US- 20020164488-\$ or US- 20040175549-\$ or US- 20040094871-\$ or US- 20030170415-\$ or US-	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/30 13:57

		20020150789-\$ or US- 20020051848-\$ or US- 20050014031-\$ or US- 20040207072-\$ or US- 20030203225-\$ or US- 20030089975-\$ or US- 20030044653-\$ or US- 20030098632-\$ or US- 20040074586-\$ or US- 20050029244-\$).did. or (US-20050011878-\$ or US- 20040217105-\$ or US- 20040060919-\$ or US- 20050112810-\$).did. or (US-6483185-\$ or US- 6033787-\$ or US- 6707671-\$ or US- 6054198-\$ or US- 6214446-\$ or US- 6013357-\$ or US- 6311888-\$ or US- 6522555-\$ or US- 6309737-\$ or US- 5354415-\$ or US- 4876119-\$ or US- 5807626-\$ or US- 5571603-\$ or US- 4929433-\$ or US- 4699310-\$ or US- 4602731-\$ or US- 4552301-\$ or US- 5213877-\$ or US- 7189449-\$ or US- 7170186-\$ or US- 6877651-\$ or US- 6485816-\$ or US- 6328198-\$ or US- 4693409-\$ or US- 5834840-\$ or US- 5392982-\$).did. or (US- 5248079-\$ or US- 5654246-\$ or US- 5420085-\$).did. or (US- 2460334-\$).did.				
S84	40	S83 ((boron adj nitride) or BN)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 13:57
S85	3521	((release\$4 near2 agent) ((boron adj nitride) or BN))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 14:03

S86	124	S85 ((metal ceramic) SAME (bond or join\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 14:03
S87	15	S86 (crystal\$4 with (grain or strain))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2008/07/30 14:03

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